

ACER_BAP31

MAIN BOARD

2008.12.29

Tuesday, March 10, 2009		X01
DATE	CHANGE NO.	REV

	EE	DATE	POWER	DATE	INVENTEC			
DRAWER					TITLE ACER_JM31			
DESIGN								
CHECK								
RESPONSIBLE								
SIZE=					SIZE	CODE	DOC NUMBER	REV
FILE NAME: XX00-XXXXXX00					C	X01	D-CS-1310A2264501.AJG	X01
PNL	XX0000000000				SHEET 1 of 36			

1. Schematic Page Description :

Montevina Schematic Ver : X01

1. Title

2. Schematic Page DESCR

3. Block Diagram

4. Annotations

5. Schematic Modify

6. Timing Diagram

7. Power Block Diagram

8. Adaptor in/Charge

9. 5VLA/5VA/3VA

10. 3VS/5VS/1.5V (DDR3)

11. 1.05VS/1.5S/1.8V/1.5VA

12. Power Latch/1.5VS/SCREW HOLE

13. CPU Core Power

14. GPU Core Power

15. Penryn Processor(1/2)

16. Penryn Processor(2/2)

17. CPU Thermal

18. Cantiga Host(1/6)

19. Cantiga DMI/Graph(2/6)

20. Cantiga DDRII(3/6)

21. Cantiga Power(4/6)

22. Cantiga Power(5/6)

23. Cantiga Ground(6/6)
24. Clock Generator

25. DDR3 SDRAM SO-DIMM0

26. DDR3 SDRAM SO-DIMM1

27. ICH9M CPU/IDE/SATA(1/4)

28. ICH9M PCI/PCIE/DMI/USB(2/4)

29. ICH9M GPIO(3/4)

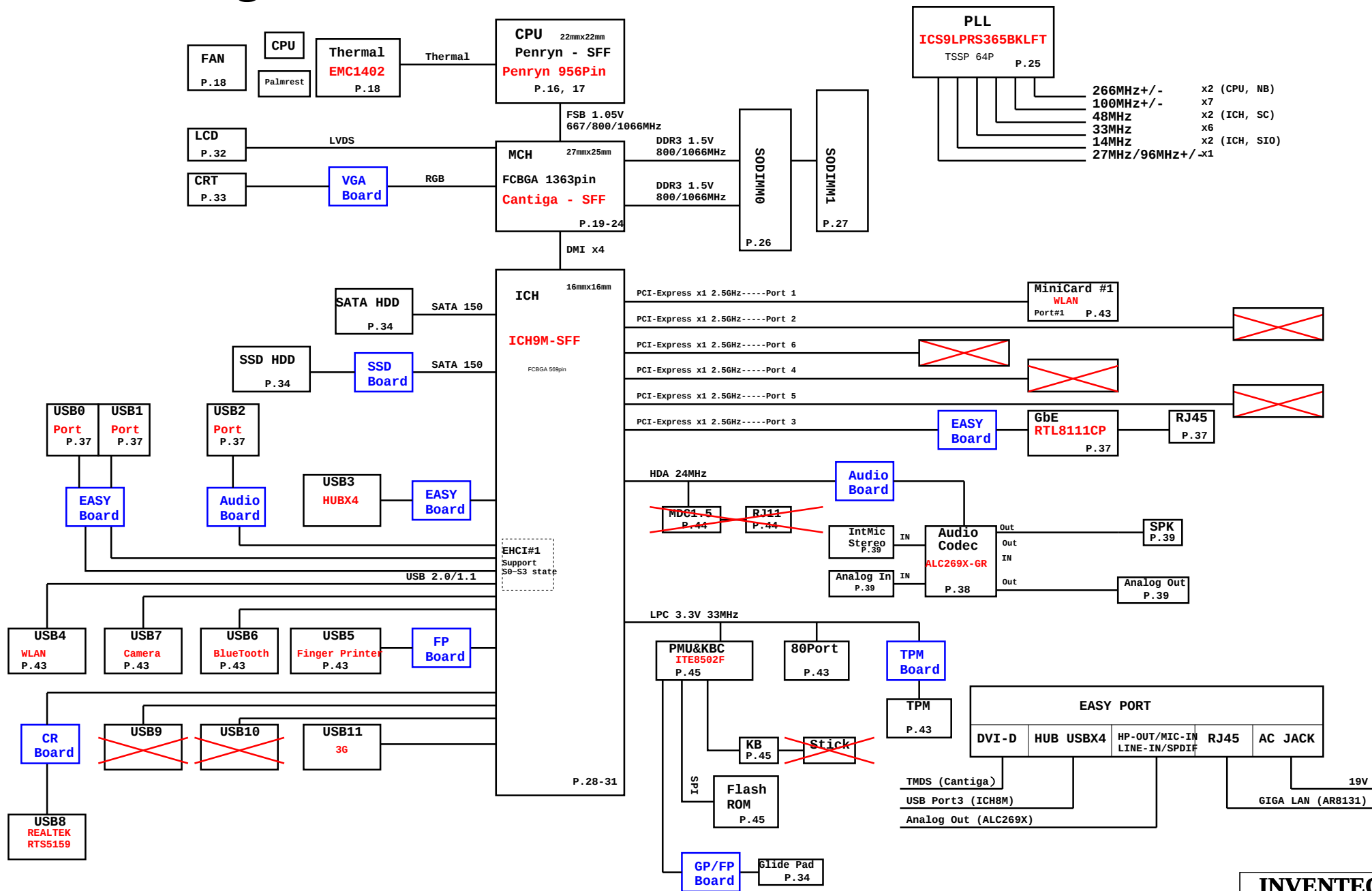
30. ICH9M Power/GND(4/4)

31. LCD CNN/SATA/3G/WLAN

32. KBC ITE8512F

33. IO CN

3. Block Diagram :



INVENTEC

TITLE
BAP31 (Penryn+Cantiga+ICH9M)SFF
Block Diagram

SHEET

4. Net name Description :

Voltage Rails

DCIN	Primary DC system power supply
+5VLA	5.0V always on power rail by LATCH or ACIN
+5VA	5.0V always on power rail by ECPWON
+3VA	3.3V always on power rail by ECPWON
+5VS	5.0V switched power rail by SLP_S3#_3R
+3VS	3.3V switched power rail by SLP_S3#_3R
+1.8VS	1.8V switched power rail by SLP_S3#_3R
VCC_CORE	Core Voltage for CPU
+1.05VS	1.05V power rail for AGTL+ termination/Core for GMCH by SLP_S3#_3R
+1.25VS	1.25V switched power rail by SLP_S3#_3R
+1.5VS	1.5V power rail for CPU PLL/DMI;PCIE;DDRIII DLLs for GMCH/Core;PCIE for ICH9m by SLP_S3#_3R
+1.5V	1.5V power rail for DDRII by SLP_S5#_3R
0.75VDDT_DDRIII	0.75V DDRII Termination Voltage by SLP_S3#_3R

Part Naming Conventions

C	=	Capacitor
CN	=	Connector
D	=	Diode
F	=	Fuse
L	=	Inductor
Q	=	Transistor
R	=	Resistor
RP	=	Resistor Pack
U	=	Arbitrary Logic Device
Y	=	Crystal and Osc

Net Name Suffix

#	=	Active Low signal
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5. Board Stack up Description

PCB Layers

Layer 1		Component Side, Microstrip signal Layer
Layer 2		Ground Plane
Layer 3		Stripline Layer
Layer 4		Power Plane
Layer 5		Stripline Layer
Layer 6		Stripline Layer
Layer 7		Ground Plane
Layer 8		Solder Side, Microstrip signal Layer

	Differential Impedance for Microstrip	Differential Impedance for Stripline
Host Clock	95 ohm +/- 20%	95 ohm +/- 20%
PCI-E Clock	95 ohm +/- 20%	95 ohm +/- 20%
DDR3 CLK	75 ohm +/- 20%	75 ohm +/- 20%
DDR3 Strobe	90 ohm +/- 20%	90 ohm +/- 20%
DMI Bus	95 ohm +/- 20%	95 ohm +/- 20%
PCIE Bus	95 ohm +/- 20%	95 ohm +/- 20%
SDVO	95 ohm +/- 20%	95 ohm +/- 20%
SATA	95 ohm +/- 20%	95 ohm +/- 20%
USB	90 ohm +/- 20%	90 ohm +/- 20%
LVDS	95 ohm +/- 20%	95 ohm +/- 20%
Lan	95 ohm +/- 20%	95 ohm +/- 20%

Power Rail	Destination	Voltage	S0 Current
VCC_CORE	Penryn SFF HFM: LFM:	1.3319V-1.4375V-1.4591V 0.9221V-0.9625V-0.9739V	18A
1.05VS	Penryn SFF : AGTL+ termination Cantiga GS: Core Cantiga GS: PCIE Cantiga GS:Core+HMEL+HSIO Cantiga GS:VCC_GMCH Cantiga GS:VCCA_SM_CK and NCTF Cantiga GS:VCC_DMI Cantiga GS:VCCA_SM Cantiga GS:VTT ICH9M:VCC1_05 ICH9M:DMI ICH9M:CPU_IO	1V-1.05V-1.10V 0.997V-1.05V-1.102V 0.9975V-1.05V-1.1025V 0.9975V-1.05V-1.1025V 0.997V-1.05V-1.102V 0.997V-1.05V-1.102V 0.997V-1.05V-1.102V 0.997V-1.05V-1.102V 0.997V-1.05V-1.102V 0.997V-1.05V-1.102V	4.5A 8.7A 1.78A 2.898A 10.154A 37.95mA 456mA 747.5mA 852mA 1.634A 48mA 2mA
1.5VS	Penryn SFF PLL Cantiga GS: QDAC Cantiga GS: LVDS Cantiga GS: TVDAC Cantiga GS: Various PLLS analog supply Cantiga GS: VCC_SM_CK Cantiga GS: VCC_SM ICH9M:PCIE_ICH ICH9M:SATA_ICH ICH9M:VCC_GLAN Mini Card: Express Card:	1.425V-1.5V-1.575V 1.425V-1.5V-1.575V 1.71V-1.8V-1.89V 1.425V-1.5V-1.575V 1.425V-1.5V-1.575V 1.425V-1.5V-1.575V 1.425V-1.5V-1.575V 1.425V-1.5V-1.575V 1.425V-1.5V-1.575V 1.425V-1.5V-1.575V	130mA 0.5mA 60.31mA 35mA 485mA 149.5mA 3.1625A 646mA 1.342A 80mA 650mA
1.5V	Cantiga GS: DDRIII System Memory	1.425V-1.5V-1.575V	3.1A(800M) 4.1A(1067M)
0.75VDDT_DDRIII	DDRIII Terminator:	0.7125V-0.75V-0.7875V	1.0A
3VS	Cantiga GS: HV CMOS Cantiga GS: VCCS_TV DAC ICH9M:VCC3_3 ICH9M:VCCGLAN3_3 Thermal Sensor: Mini Card: UMTS Express Card: CLK Generator: ICS9LPRS365BKLFT Mini Card: WirelessLan Bluetooth: Super I/O: IT8305E Azalia Codec: ALC262 Azalia MDC:	3.135V-3.3V-3.465V 3.135V-3.3V-3.465V 3.135V-3.3V-3.465V 3.135V-3.3V-3.465V 3.0V-3.3V-3.6V 3.135V-3.3V-3.465V 3.135V-3.3V-3.465V 3.0V-3.3V-3.6V 3.0V-3.3V-3.6V	105.3mA 78mA 308mA 1mA 5mA 1.3A 500mA
1.8VS	DVI	3.0V-3.3V-3.6V	120mA
3VA	ICH9M: RTC ICH9M:VCCSUS3_3 ICH9M:VCCCL3_3 ICH9M:VCCLAN3_3 LCD: Lan:AR8131 Azalia MDC: Flash ROM: BIOS	2V-3.3V-3.465V 3.135V-3.3V-3.465V 3.135V-3.3V-3.465V 3.135V-3.3V-3.465V 3.0V-3.3V-3.6V 3.0V-3.3V-3.6V 3.0V-3.3V-3.6V	6uA 212mA 73mA 78mA 2A 1A
5VS	Cardreader: RTS5159 Azalia Codec: ALC269 HDD: SATA ODD: SATA Audio AMP: G1432 Inverter: WebCam	3.0V-3.3V-3.6V 3.0V-3.3V-3.6V 4.75V-5.0V-5.25V 4.75V-5.0V-5.25V 4.75V-5.0V-5.25V	Max: 1.5A ; R/W: 460mA ; STDBY: 70mA Max: 1.5A ; R/W: 900mA ; STDBY: 45mA
5VA	USB: x 2 ports USB	4.75V-5.0V-5.25V 5VA 5VA	1A 2A 1.5A
5VLA	Control Power		
3VLA	EC: ITE8512E	3.0V-3.3V-3.6V	300mA

INVENTEC			
BAP31 (Penryn+Cantiga+ICH9M)SFF			
ANNOTATIONS			
SIZE	CODE	DOC NUMBER	REV
Custom	X01	D-CS-1310A264501-ALG	X01
SHEET		4	of 36

6.Schematic modify Item and History :

2009.0108

- 1. ADD USB P3 for Docking, USB P5 for Finger printer,
 Modify CN5 -----P28
- 2. Modify CN20 to 50pin-----P33
- 3. Move PWR_SWIN# from CN14 to CN20
- 4. ADD TPM module-----P34

2009.0109

- 1. ADD DOCK_USB_EN, DOCK_CRT_IN#-----P32,33

2009.0112

- 1. Change power item: R490,R291,BAT CNN TH PIN

INVENTEC

TITLE

BAP31 (Penryn+Cantiga+ICH9M)SFF

SIZE

Custom

CODE

X01

DOC NUMBER

D-CS-1310A2264501.ALG

REV

X01

CHANGE by

Milen Liu

DATE

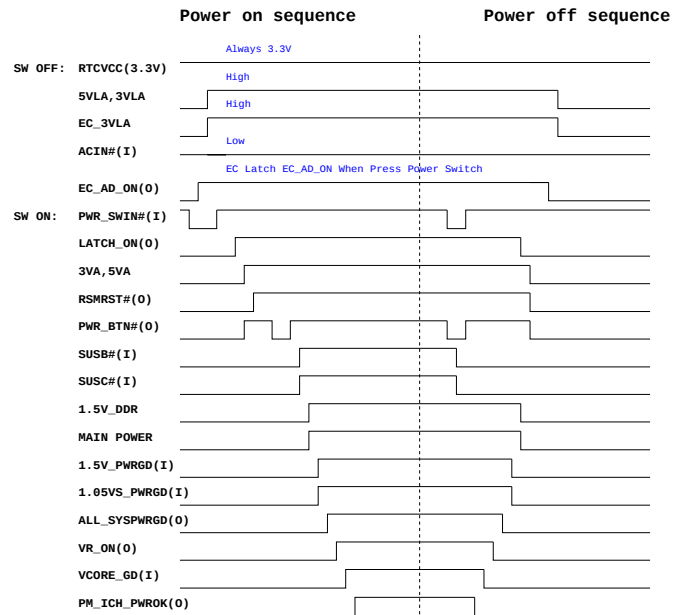
Tuesday, March 10, 2009

1

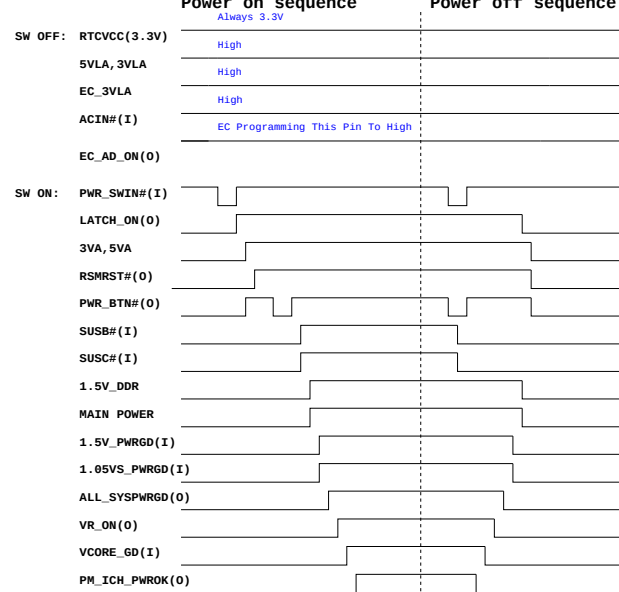
SHEET

Drawing : Wendy, Huang

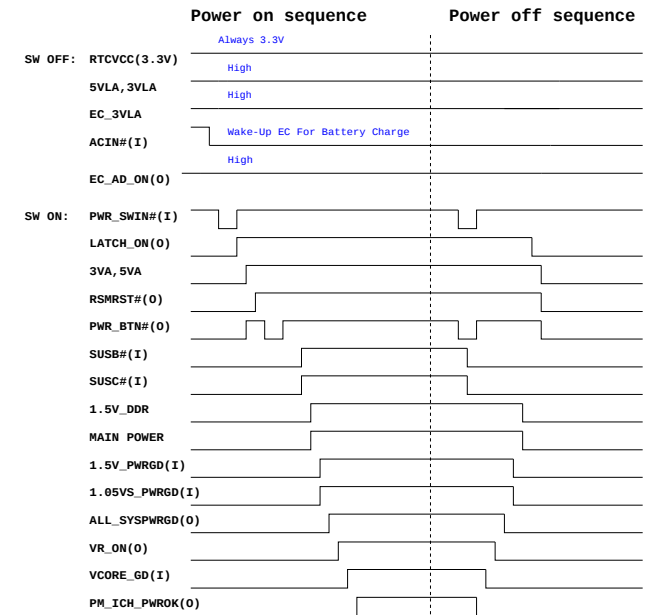
Power on/off sequence AC insert (without Battery Pack)



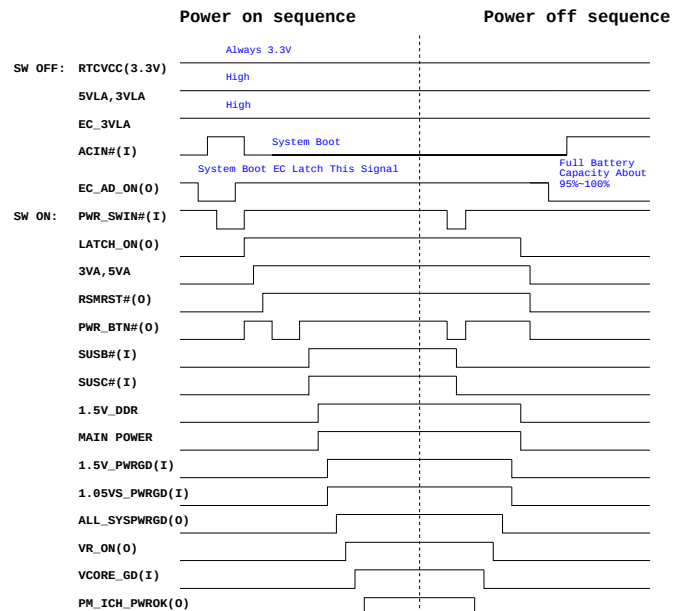
Power on/off sequence Battery insert (without AC adapter)



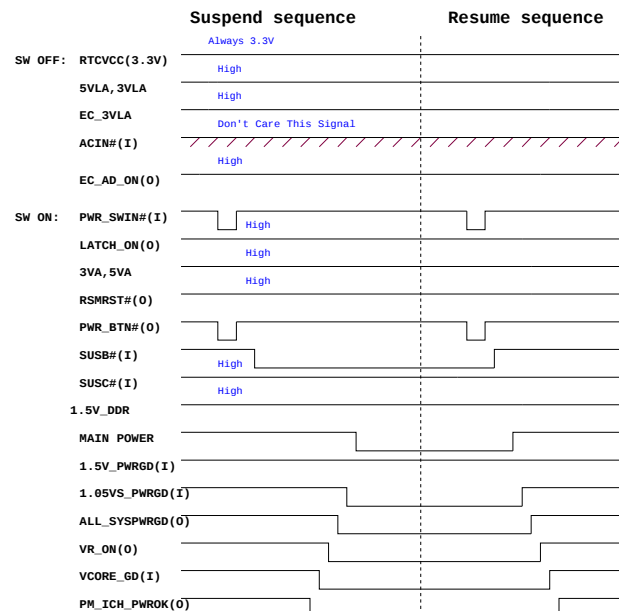
Power on/off sequence AC insert(with charge over 95%)



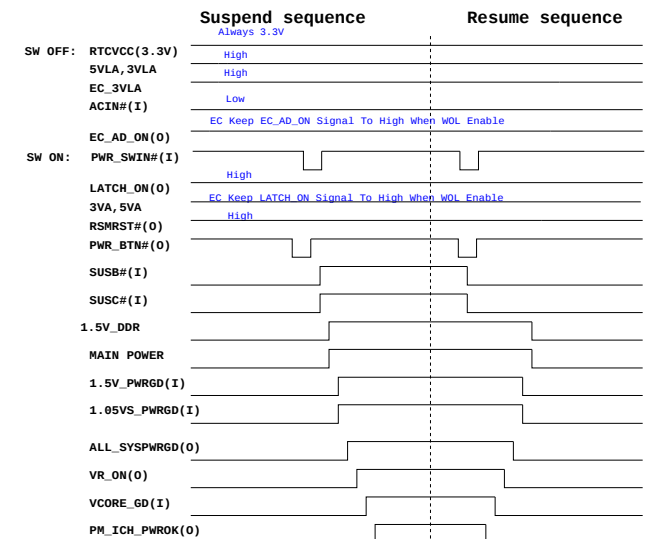
Power on/off sequence AC insert(without charge over 95%)



Suspend And Resume Sequence (S3)

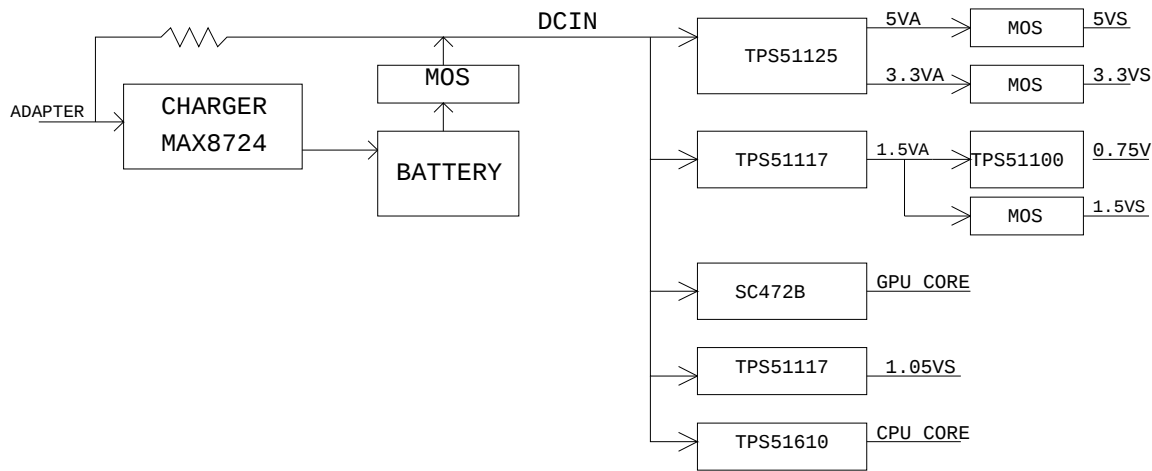


Power on/off sequence after windows shoutdown (WOL enable)

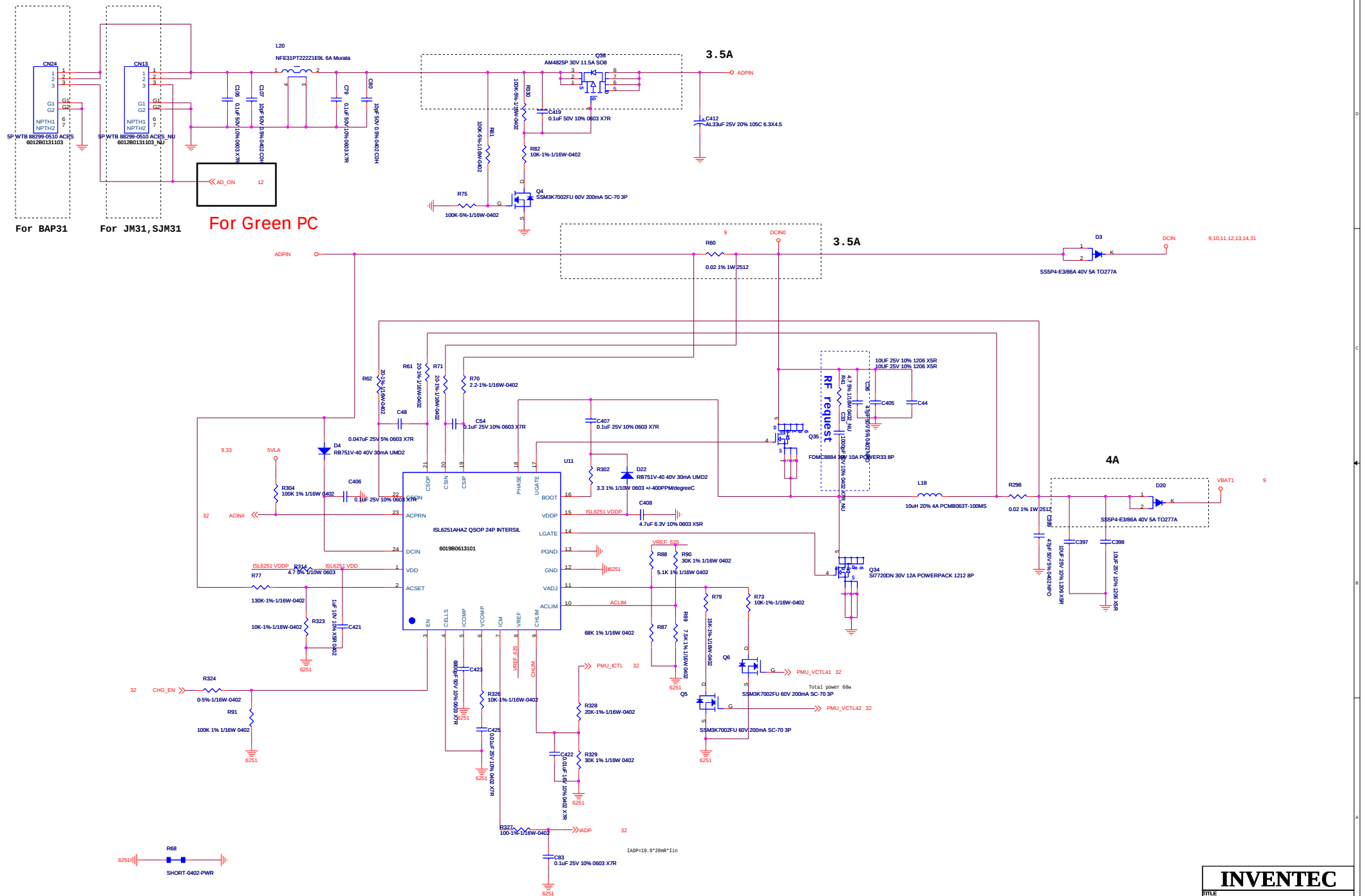
**INVENTEC**

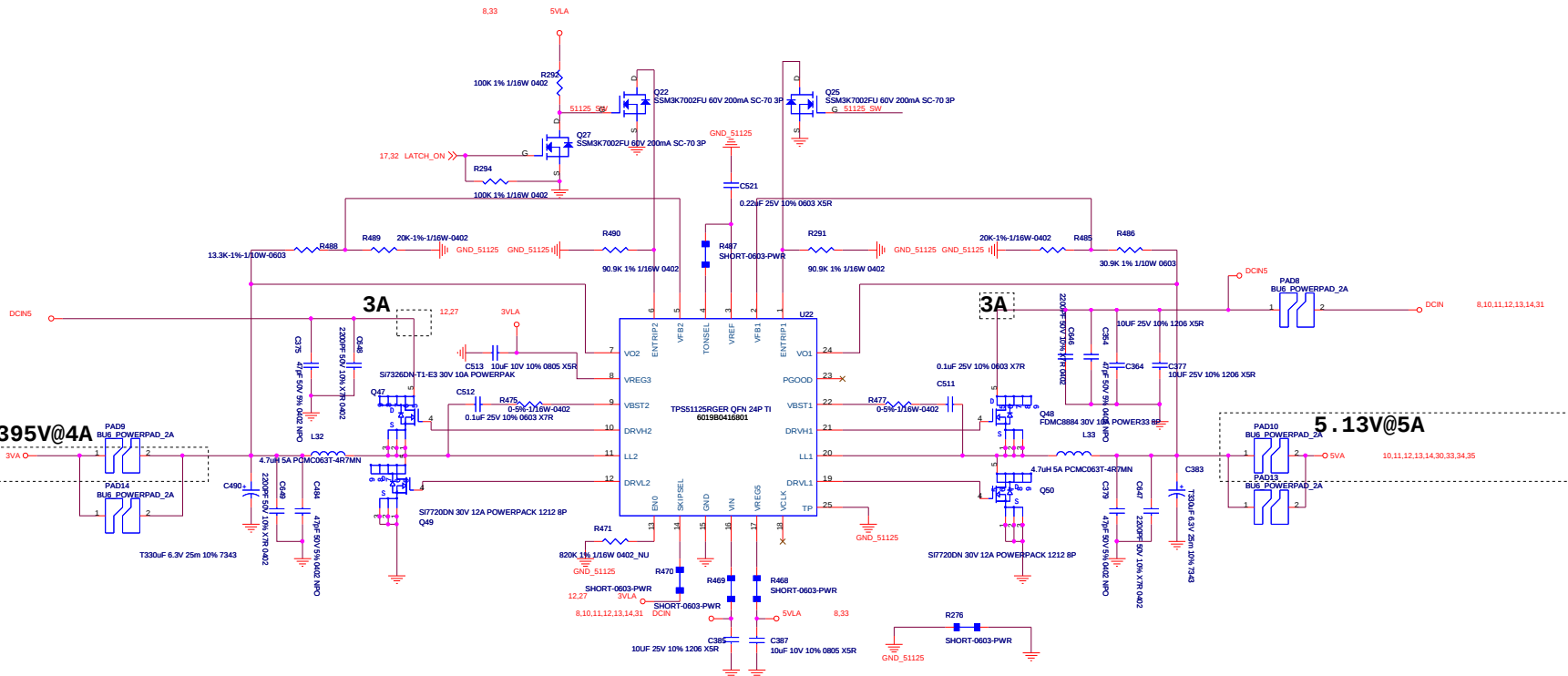
TITLE			
BAP31 (Penryn+Cantiga+ICH9M)SFF			
Time Diagram			
SIZE	CODE	DOC NUMBER	REV
Custom	X01	D-CS-1310A2264501-ALG	X01
SHEET 6 of 36			

Power Block Diagram :

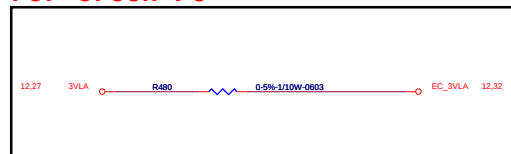


INVENTEC				
TITLE BAP31 (Penryn+Centiga+ICH9M)SFF				
Power Block Diagram				
SIZE C	CODE X01	DOC NUMBER D-CS-1310A2264501.ALG	REV X01	
SHEET				

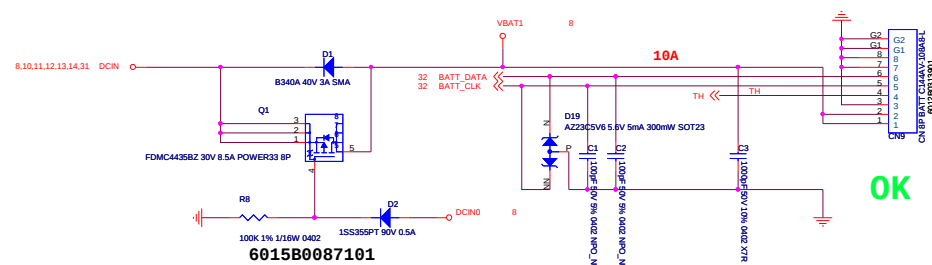
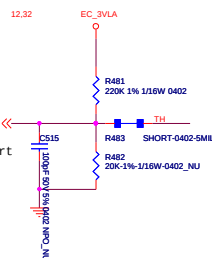




For Green PC



H: no battery
L: battery insert



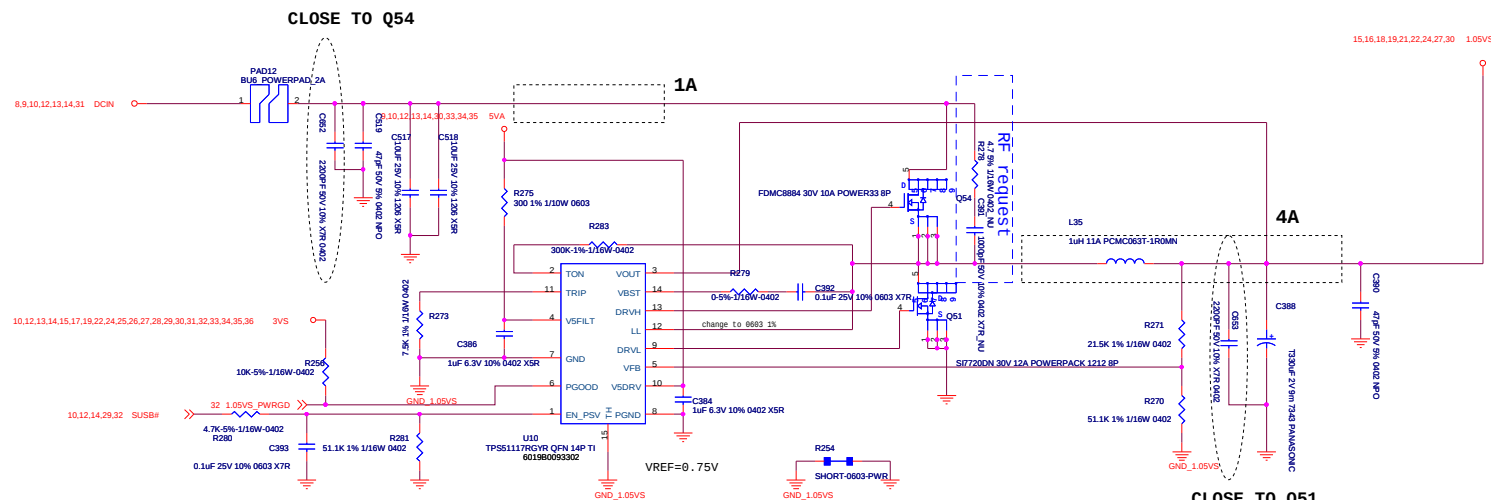
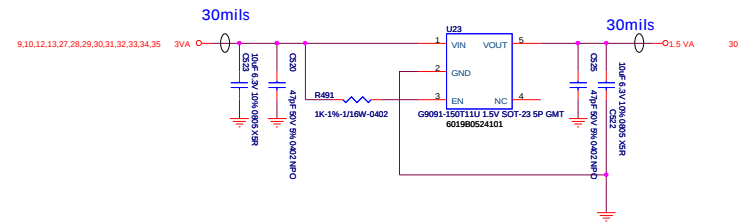
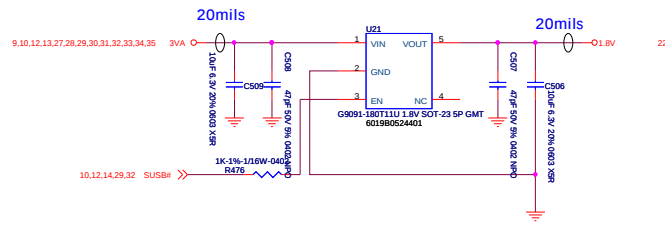
OK

INVENTEC

TITLE
BAP31 (Penryn+Catiga+ICH9M)SF
5VLA/5VA/3VLA/3VA

SIZE
Custom

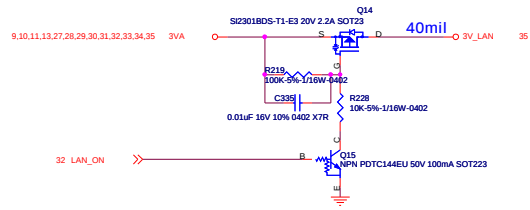
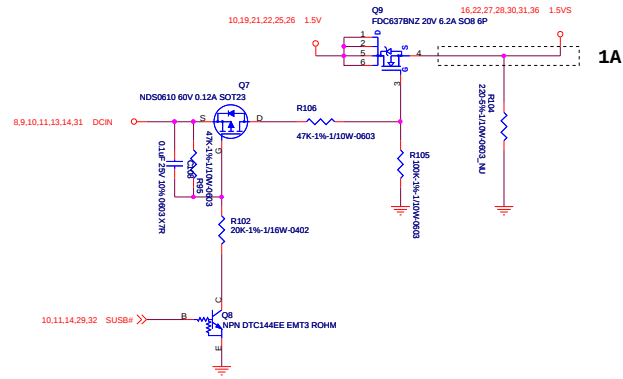
CHANGE/rev Miller Liu DATE Tuesday, March 10, 2009



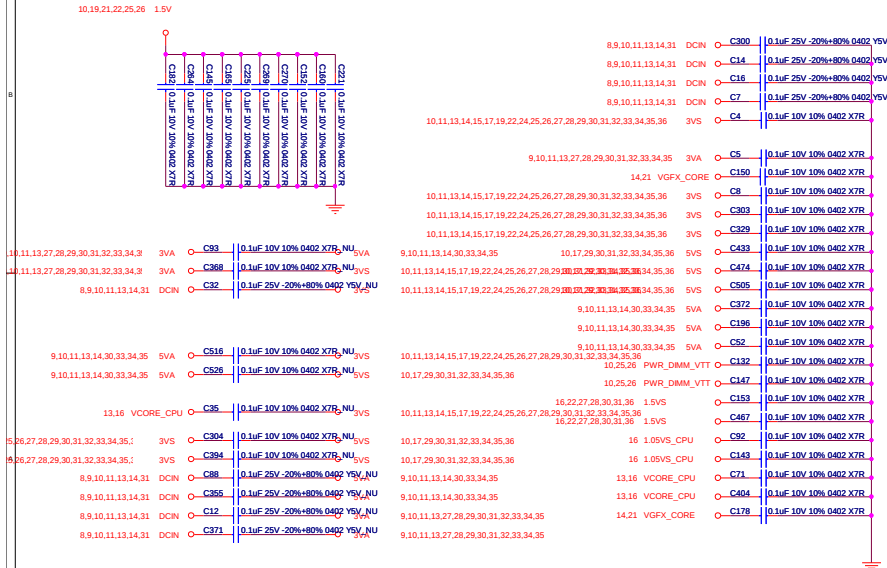
INVENTEC			
TITLE			
BAP31 (Penryn+Cantiga+ICH9M)SF			
1.05VS/1.5V/1.8V/1.5VA			
SIZE	CODE	DOC NUMBER	REV
Custom	X01	D-CS-1310A2264501-ALG	X01

CHANGE by Miller Liu DATE Tuesday, March 10, 2009

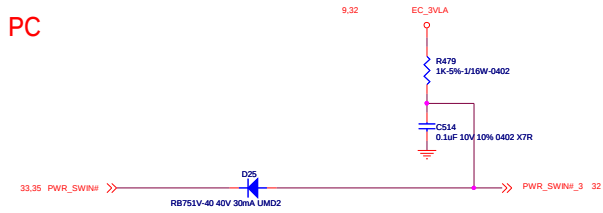
1.5VS



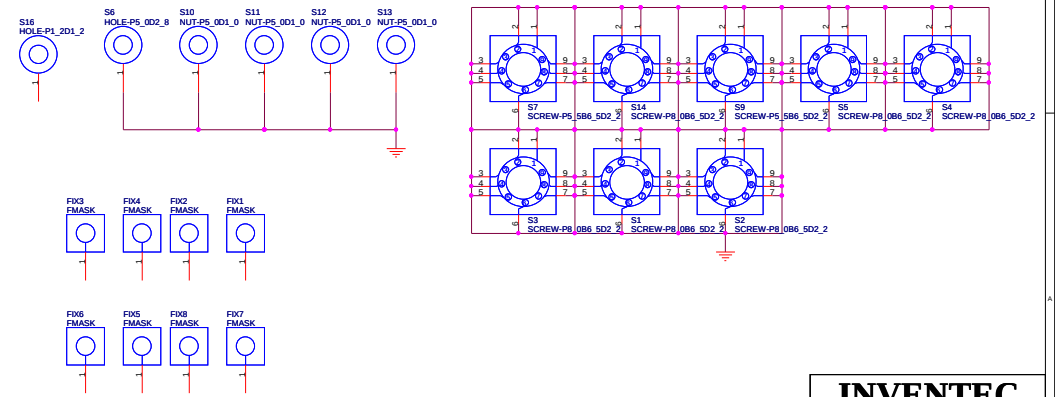
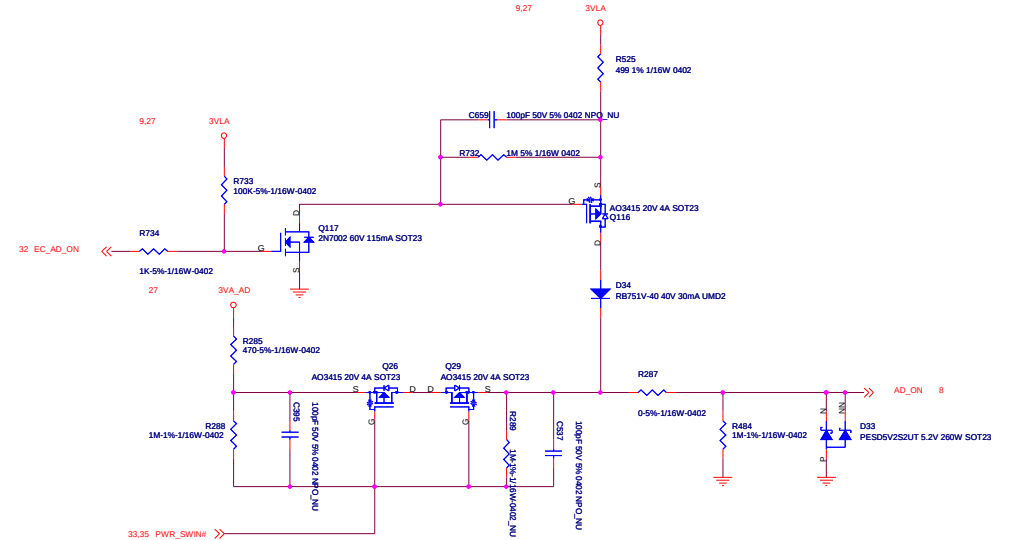
EMI Cap



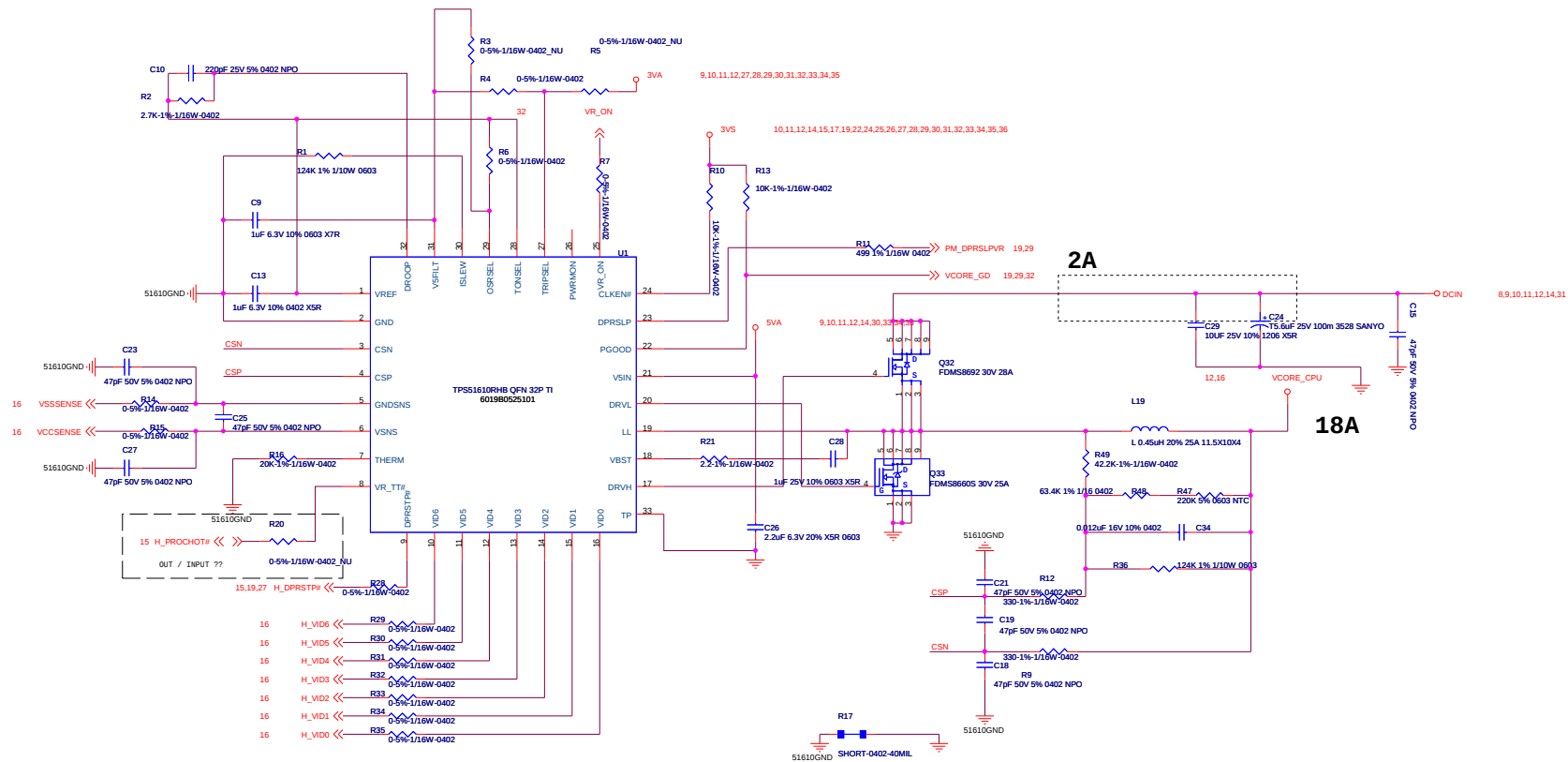
For Green PC



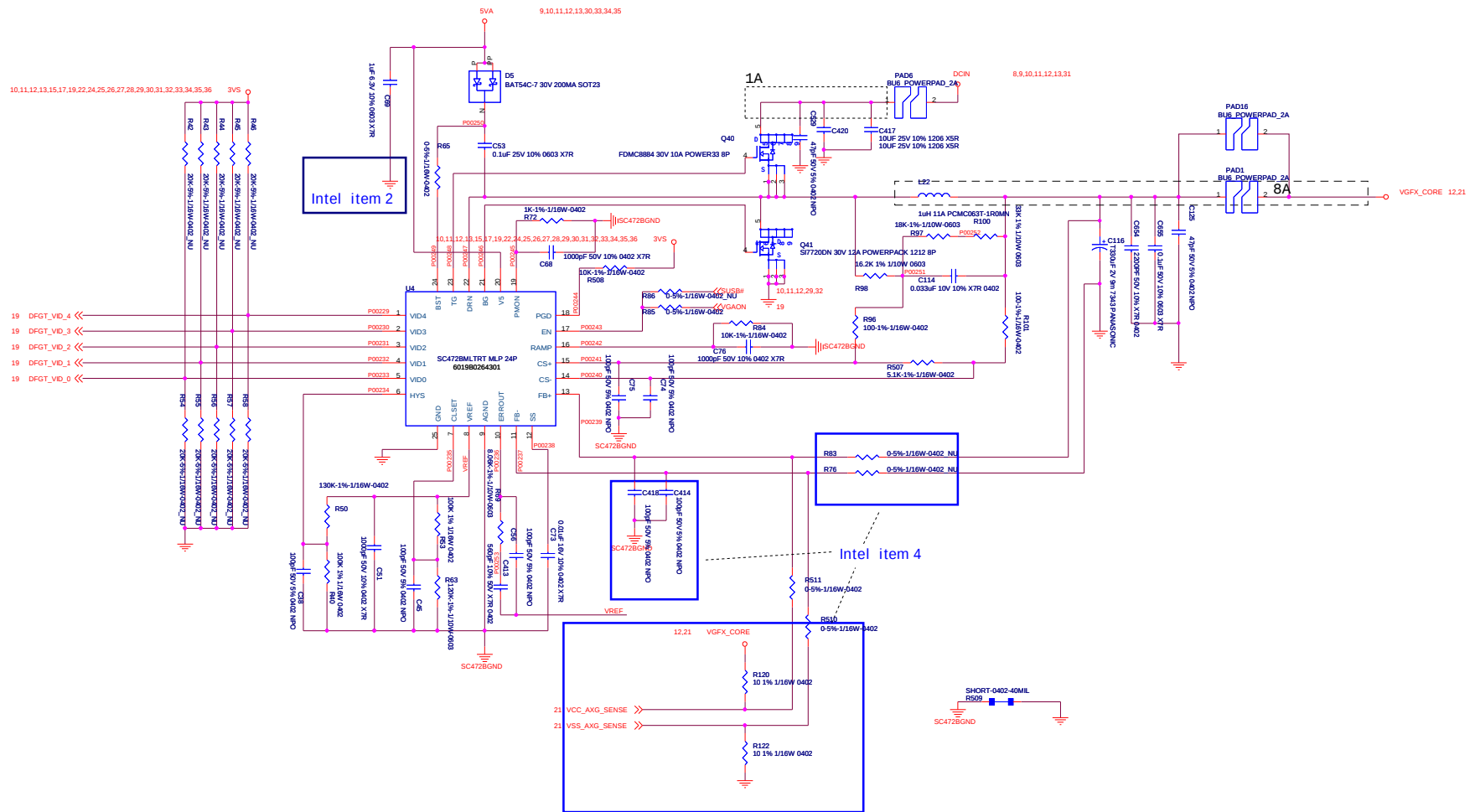
None Green PC ---- NU

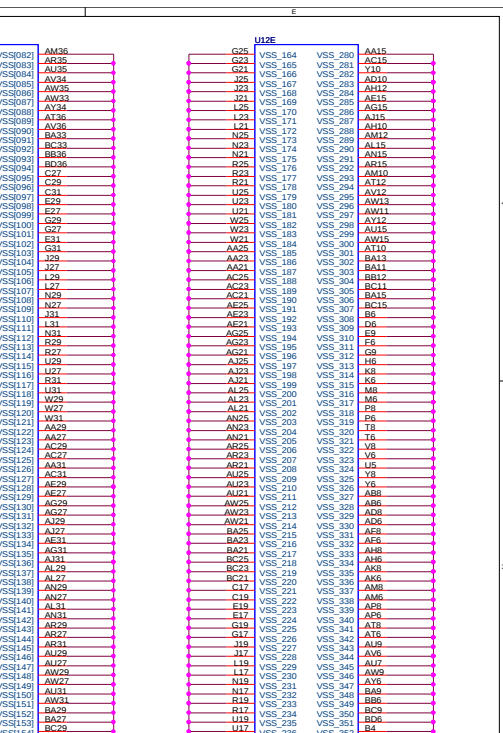


INVENTEC			
BAP31 (Penryn+Catiga+ICH9M)SF			
Power on latch			
SIZE	CODE	DOC NUMBER	REV
Custom	X01	D-CS-1310A224501-ALG	X01
CHANGE by		DATE	Tuesday, March 10, 2009
Mills Liu		SHEET 12 of 36	

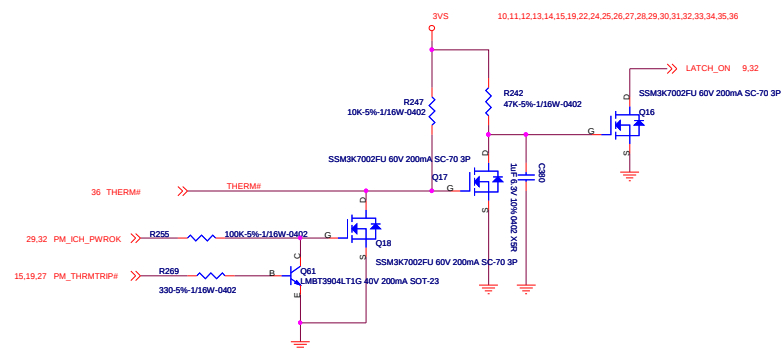


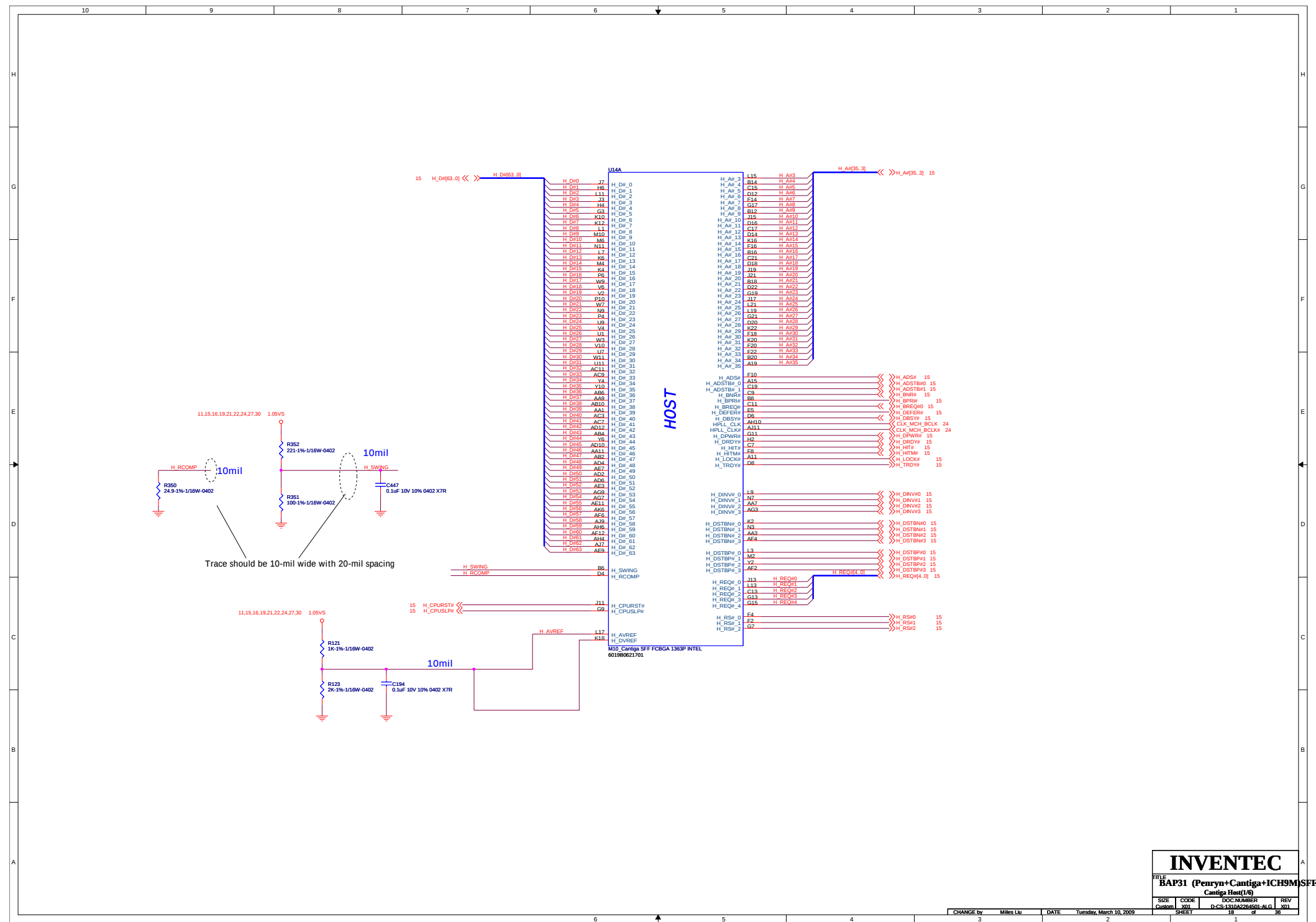
INVENTEC			
TITLE BAP31 (Penryn+Cantiga+ICH9M)SFF			
CPU Core Power			
SIZE C	CODE Y01	DOC NUMBER D-CS-1310A2264501-ALG	
SHEET		13	of

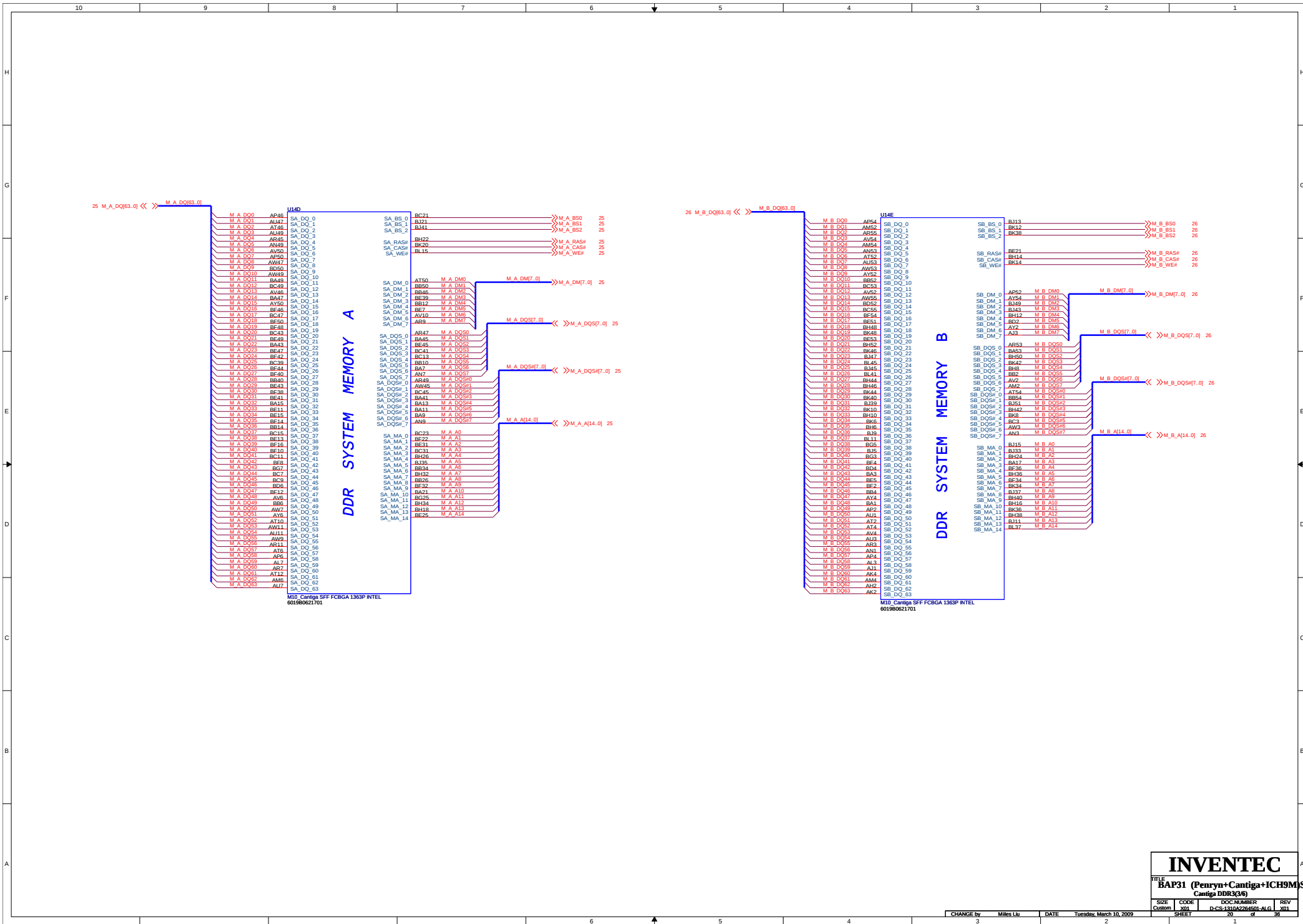


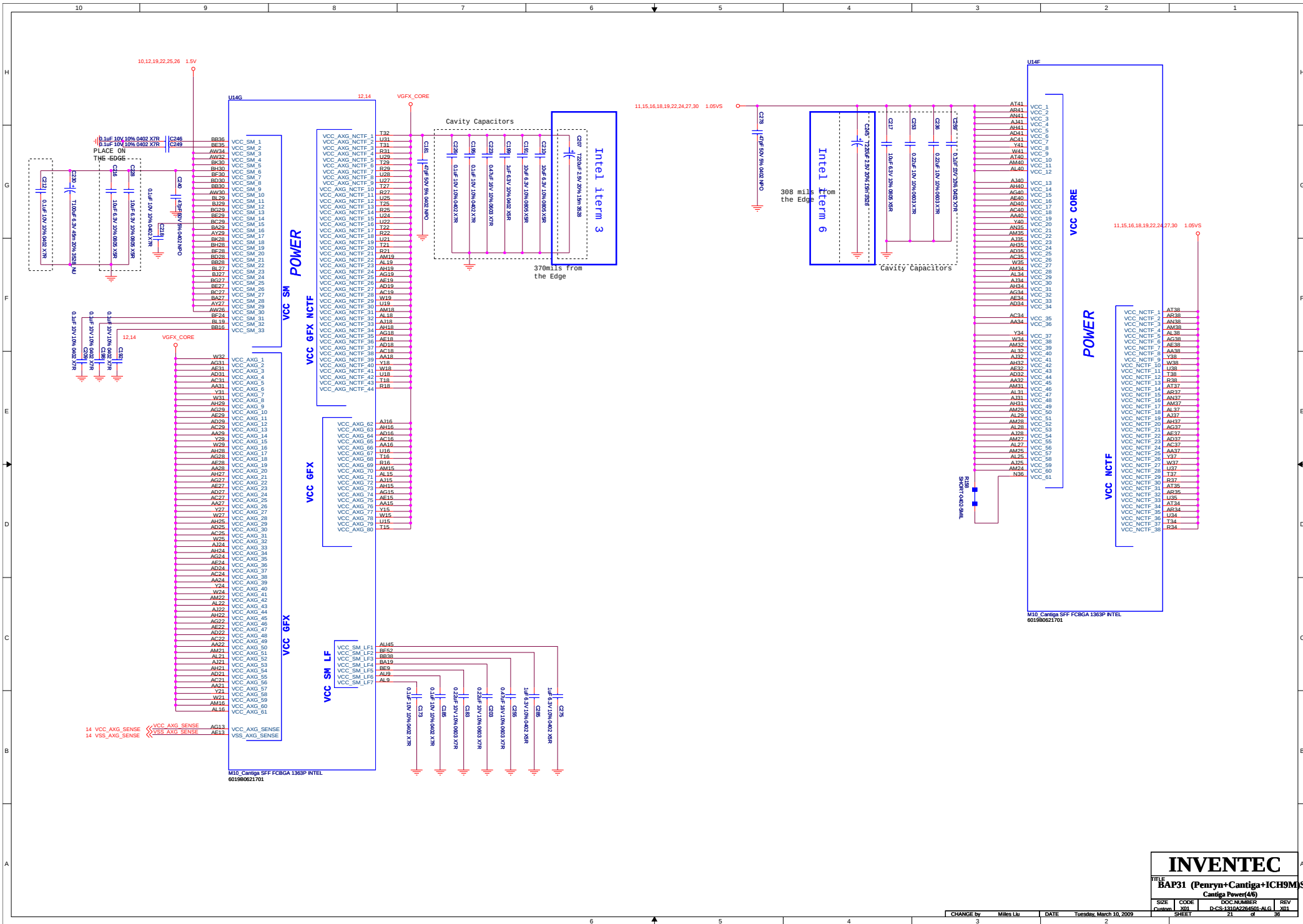


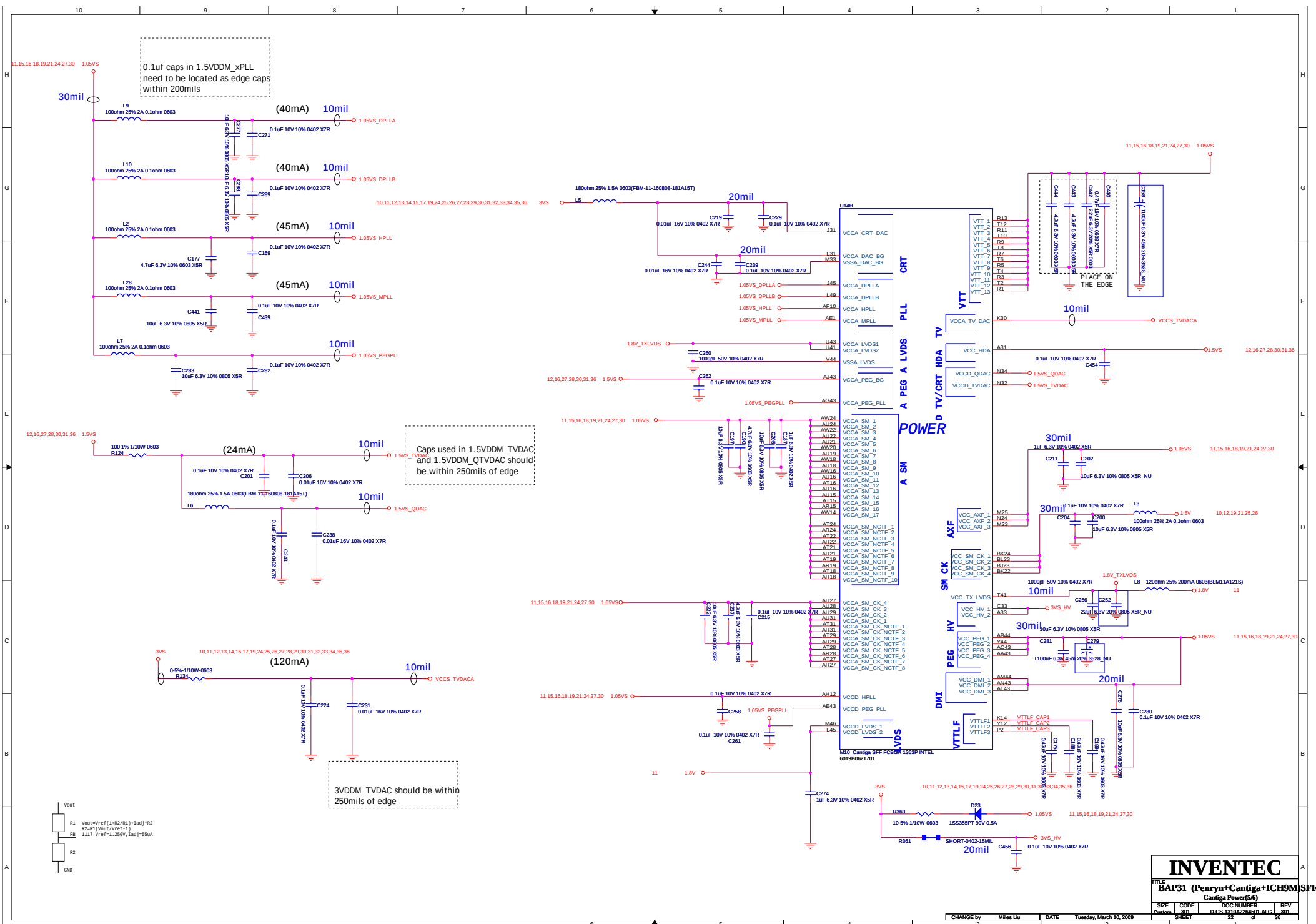
Comp0,2 connect with $Z_0=27.4\Omega$, make trace length shorter than 0.5" and width is 18mils.
Comp1,3 connect with $Z_0=55\Omega$, make trace length shorter than 0.5" and width is 5mils

[illegible][illegible]



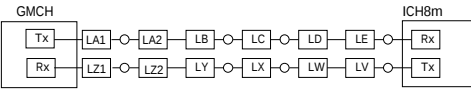
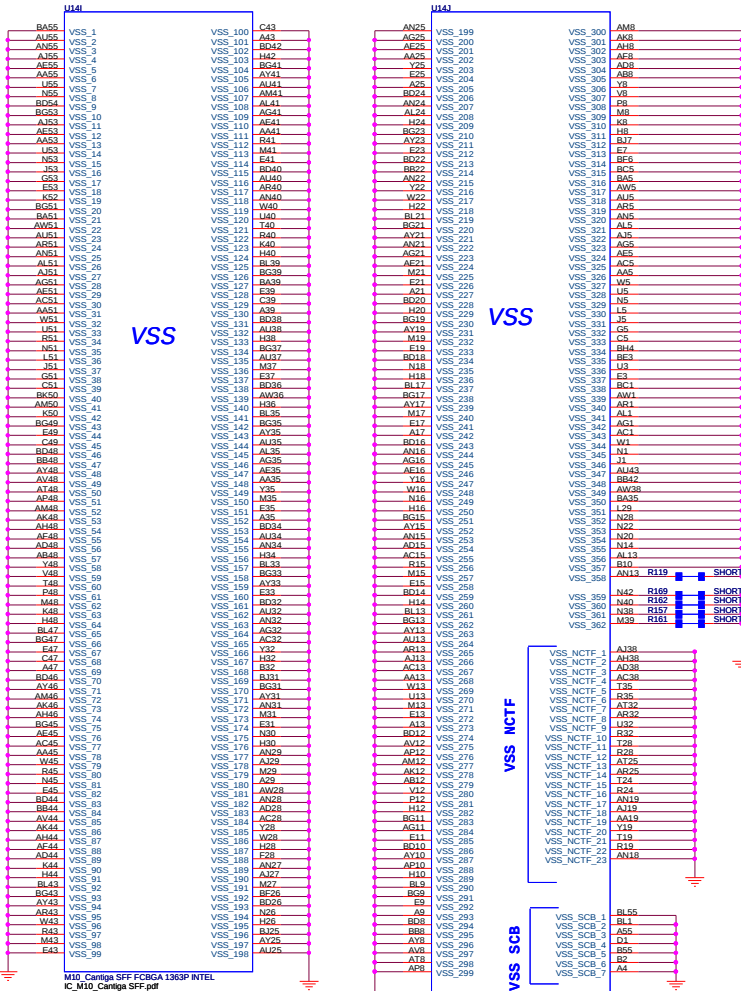






DMI Routing Guideline

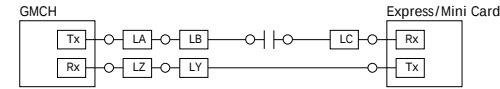
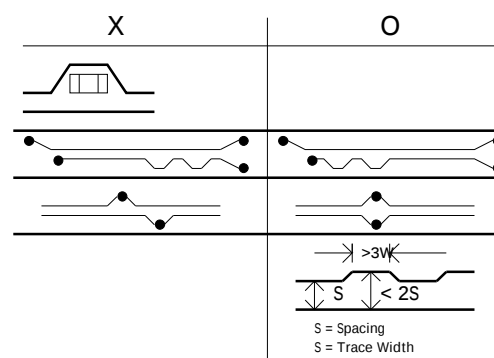
PCIe Routing Guideline



Breakout/in LA/LZ	Main Route LB/LY	Breakout/in LE/LV
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV
Stripline	Same Routing layer as LA/LZ	Same Routing layer as LE/LV
Stripline	Same Routing layer as LA/LZ	Same Routing layer as LE/LV
Stripline	Same Routing layer as LA/LZ	Same Routing layer as LE/LV
Stripline	Same Routing layer as LA/LZ	Same Routing layer as LE/LV
Stripline	Same Routing layer as LA/LZ	Same Routing layer as LE/LV

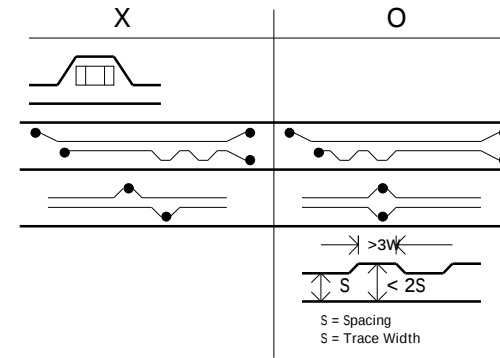
Parameter	Main Route Guideline	Breakout Guideline
Uncoupled Single End Impedance	55 +/- 15%	55 +/- 15%
Nominal Trace Width	Inner Layer : 4 mils Outer Layer : 5 mils	Inner Layer : 4 mils Outer Layer : 5 mils
Nominal Diferential Pair-Pitch	Inner Layer : 7 mils Outer Layer : 7 mils	Inner Layer : 4 mils Outer Layer : 5 mils
Pair-to-Pair Pitch	Inner Layer : 37 mils Outer Layer : 37 mils	Inner Layer : 27 mils Outer Layer : 27 mils
Bus-to-Bus Pitch	Inner Layer : 22 mils Outer Layer : 20 mils	Inner Layer : 15 mils Outer Layer : 12 mils
Reference Plane	Ground	Ground
Splits/Voids	No routing over plane splits No routing over voids	No routing over plane splits No routing over voids
Trace Length-LA (GMCH Breakout)	Max = 250 mils	
Trace Length-LB (GMCH Breakout to Via2)	Max = 3600 mils	
Trace Length-LC (Via2 to Via3)	Max = 5900 mils	
Trace Length-LD (Via3 to ICH7m Breakout)	Max = 3600 mils	
Trace Length-LE (ICH7m Breakout)	Max = 400 mils	
Trace Length-L1 (LA+LB+LC+LD+LE)	Max = 8000 mils	
Trace Length-LV (ICH7m Breakout)	Max = 400 mils	
Trace Length-LW (ICH7m Breakout to Via2)	Max = 3600 mils	
Trace Length-LX (Via2 to Via3)	Max = 5900 mils	
Trace Length-LY (Via3 to GMCH Breakout)	Max = 3600 mils	
Trace Length-LZ (GMCH Breakout)	Max = 400 mils	
Trace Length-L2 (LV+LW+LX+LY+LZ)	Max = 8000 mils	

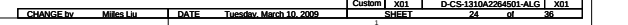
*** When routing near the edge of their reference plane , trace should maintain at least 40 mils space to the edge of the plane
*** Match the trace lengths of the complementary signals within each differential pair to +/- 5 mils

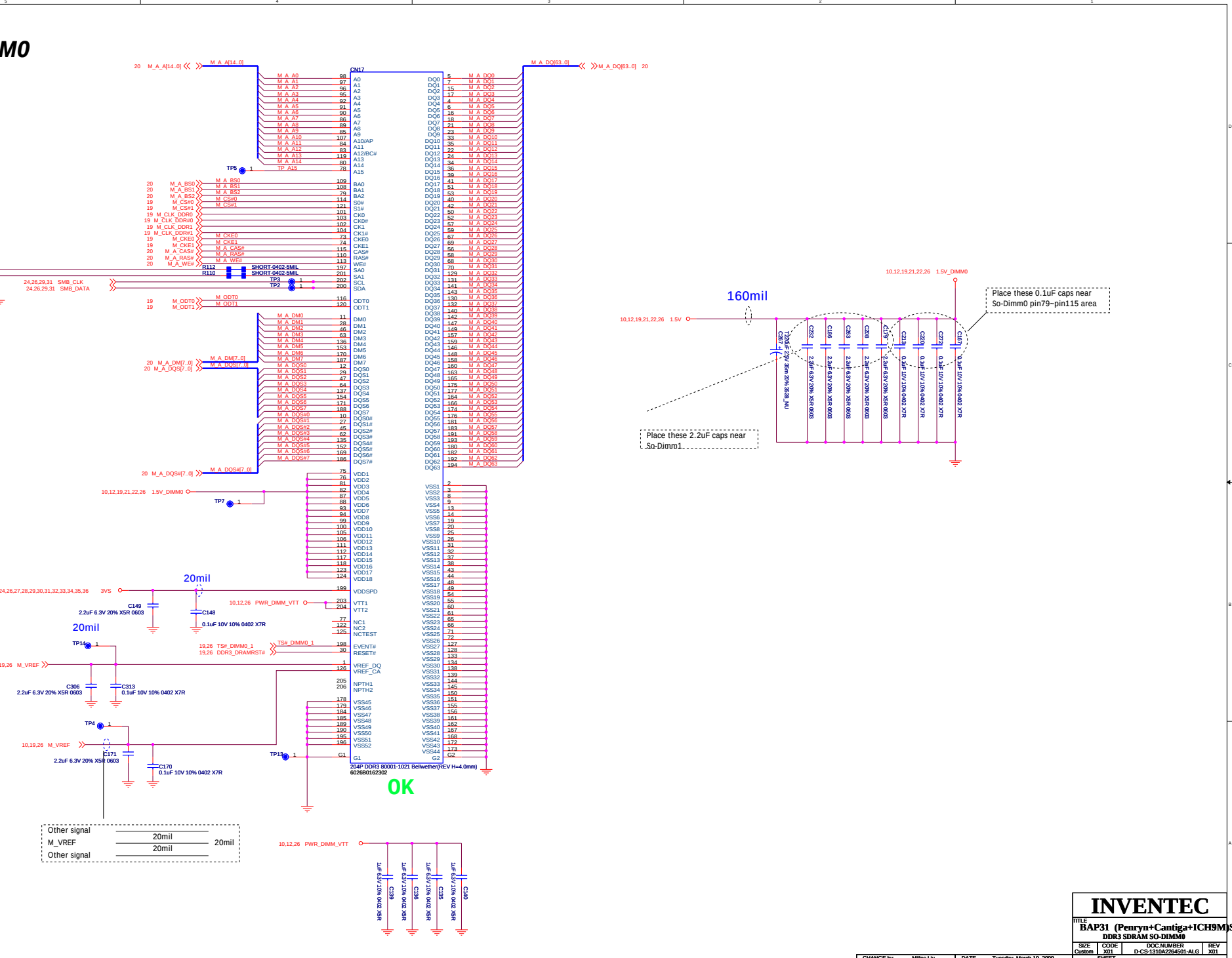


Breakout/in LA/LZ	Main Route LB/LY/LC	Main Route LD/LV	Breakout/in LE/LV
Stripline	Microstrip	Same Routing layer as LE/LV	Microstrip
Parameter	Main Route Guideline	Breakout Guideline	
Uncoupled Single End Impedance	55 +/- 15%	55 +/- 15%	
Nominal Trace Width	Inner Layer : 4 mils Outer Layer : 5 mils		
Nominal Differential Trace Space	Inner Layer : 7 mils Outer Layer : 7 mils	Inner Layer : 4 mils Outer Layer : 5 mils	
Pair-to-Pair Pitch	Inner Layer : 37 mils Outer Layer : 37 mils	Inner Layer : 27 mils Outer Layer : 27 mils	
Bus-to-Bus Pitch	Inner Layer : 20 mils Outer Layer : 20 mils	Inner Layer : 15 mils Outer Layer : 12 mils	
Reference Plane	Ground	Ground	
Splits/Voids	No routing over plane splits No routing over voids		
Trace Length-LA (ICH7m Breakout)	Max = 400 mils		
Trace Length-LB (ICH7m Breakout to AC cap)	Max = 10750 mils		
Trace Length-LC (AC cap to PCIe CN)	Max = 10750 mils		
Trace Length-L1 (LA+LB+LC)	Max = 12000 mils		
Trace Length-LY (PCIe CN to ICH7m Breakout)	Max = 11950 mils		
Trace Length-LZ (ICH7m Breakout)	Max = 400 mils		
Trace Length-L2 (LY+LZ)	Max = 12000 mils		

*** When routing near the edge of their reference plane , trace should maintain at least 40 mils space to the edge of the plane
*** Match the trace lengths of the complementary signals within each differential pair to +/- 5 mils







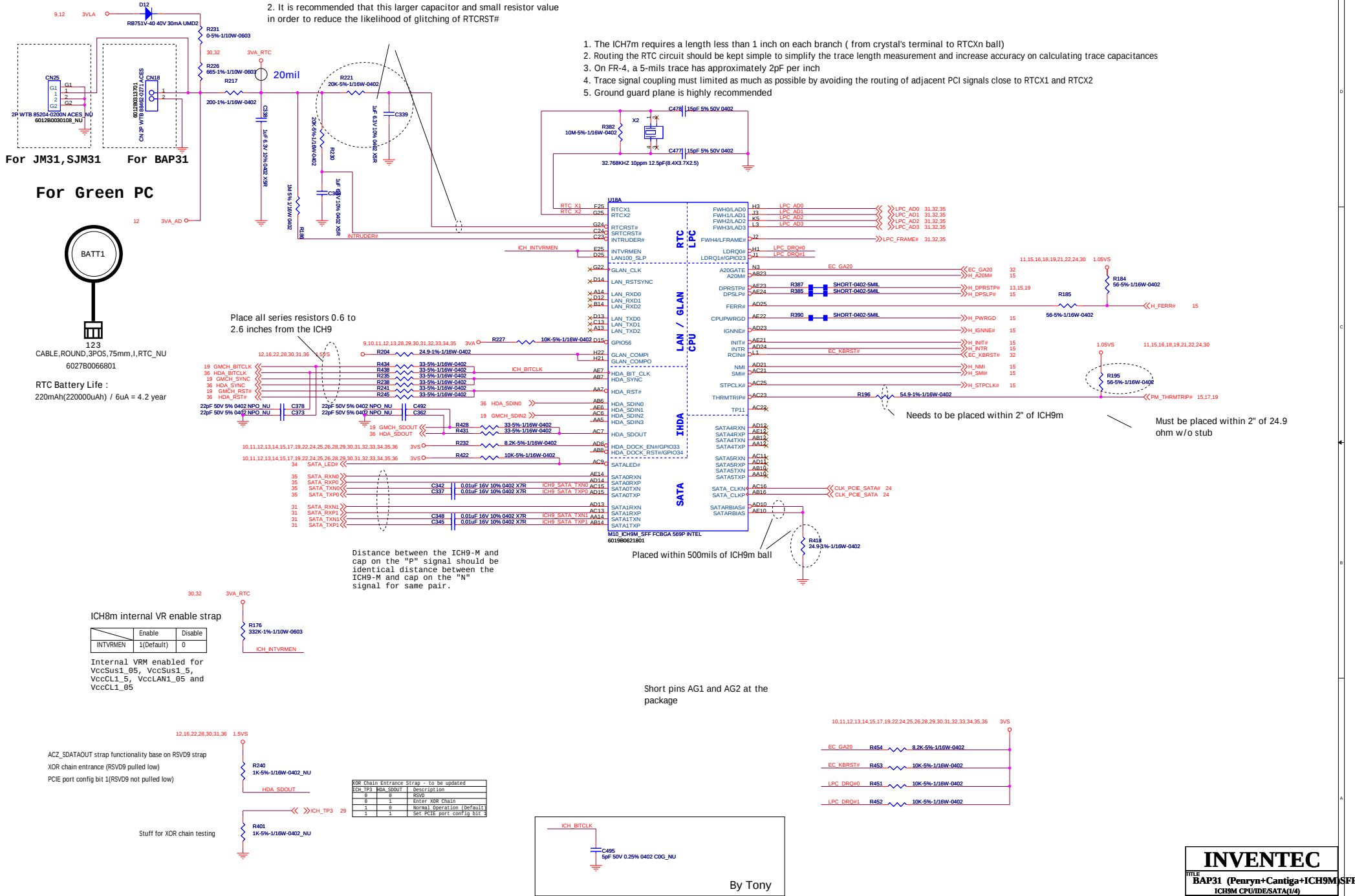
TITLE	BAP31 (Penryn+Cantiga+ICH9M)SFF DDR3 SDRAM SO-DIMM0
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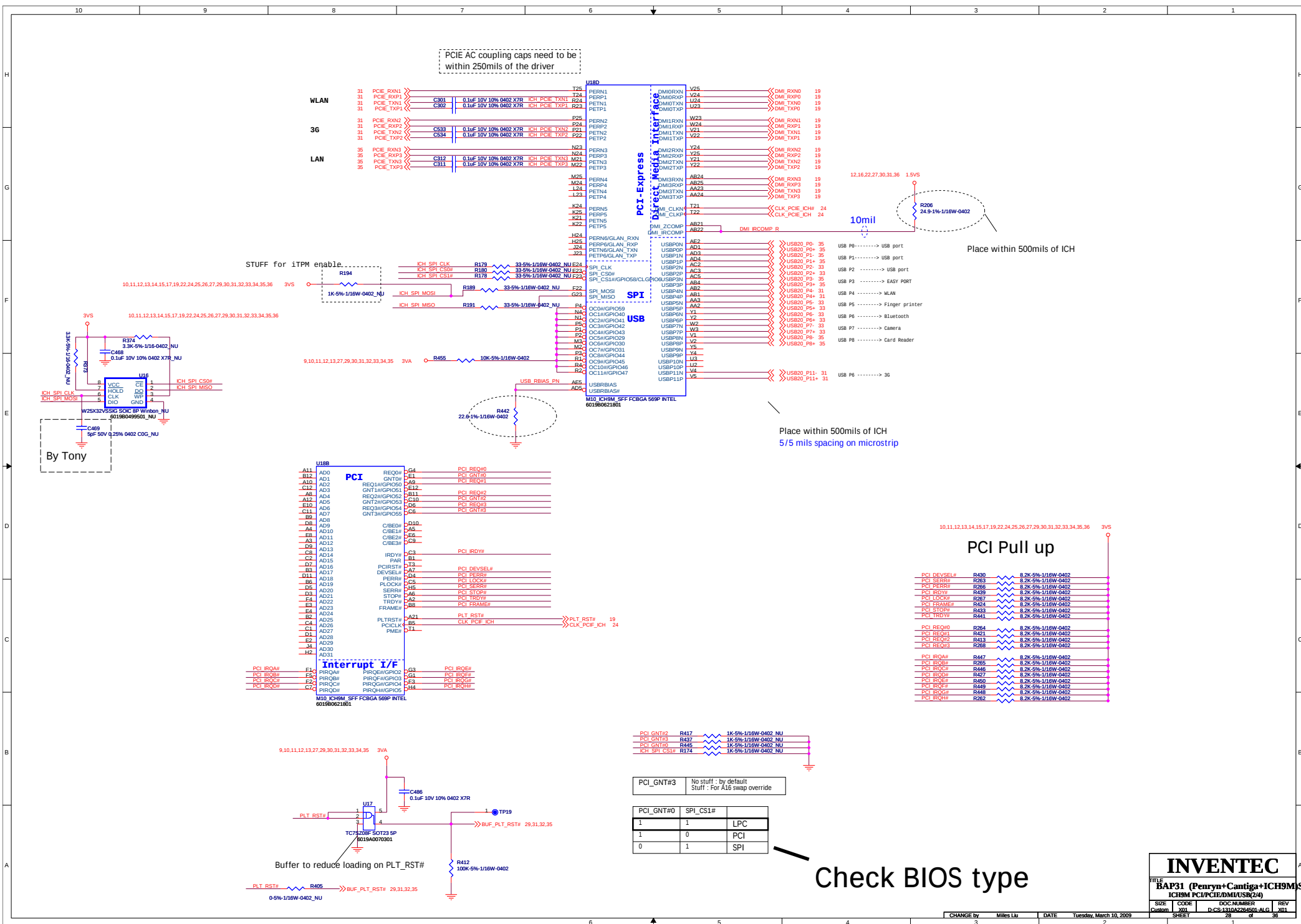
SIZE	CODE	DOC. NUMBER	REV
Custom	X01	D-CS-1310A2264501-ALG	X01

RTC Circuit

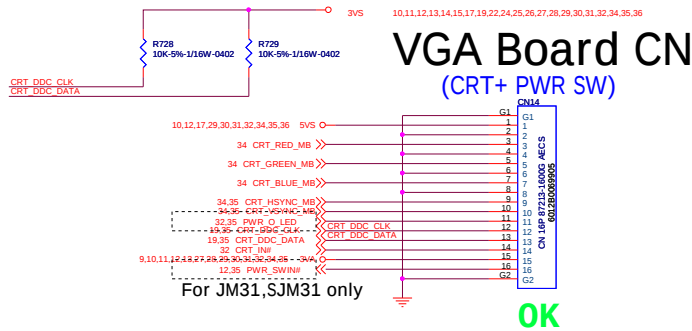
1. RC delay time should be in the range of 18-25ms
2. It is recommended that this larger capacitor and small resistor value in order to reduce the likelihood of glitching of RTCRST#

1. The ICH7m requires a length less than 1 inch on each branch (from crystal's terminal to RTCXn ball)
2. Routing the RTC circuit should be kept simple to simplify the trace length measurement and increase accuracy on calculating trace capacitances
3. On FR-4, a 5-mils trace has approximately 2pF per inch
4. Trace signal coupling must limited as much as possible by avoiding the routing of adjacent PCI signals close to RTCX1 and RTCX2
5. Ground guard plane is highly recommended

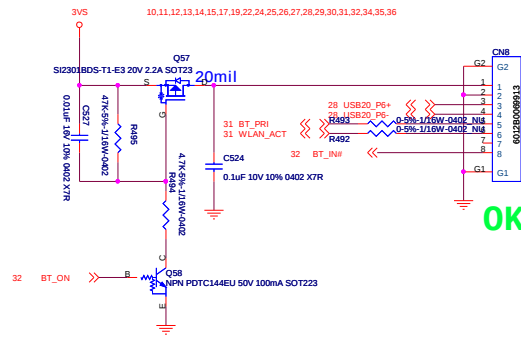






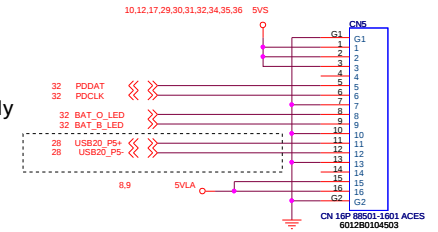


Bluetooth CON.

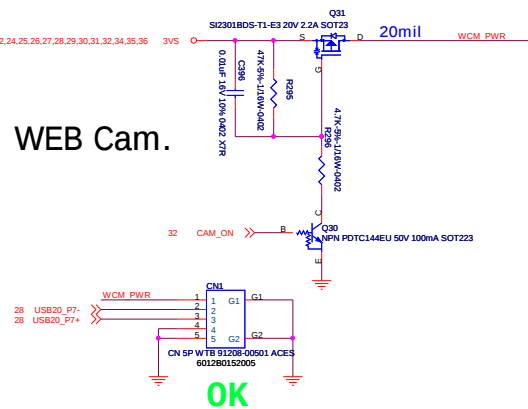


GLIDE PAD Board

For BAP31 only

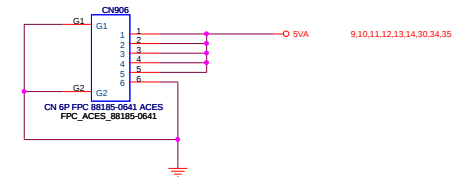
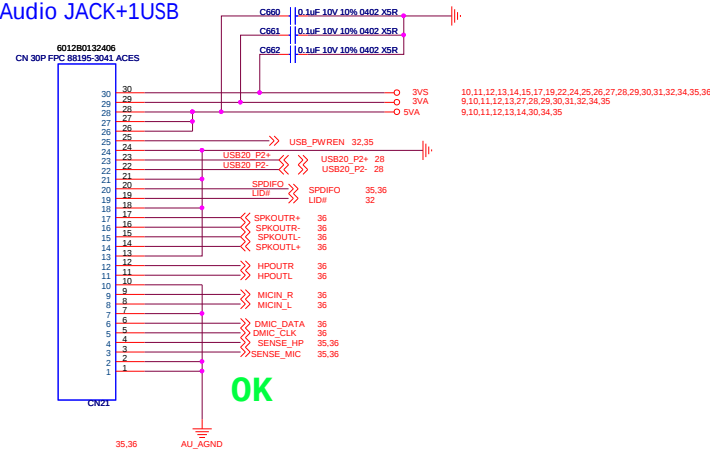


WEB Cam.



AUDIO Board CN

(Audio JACK+1USB)



INVENTEC

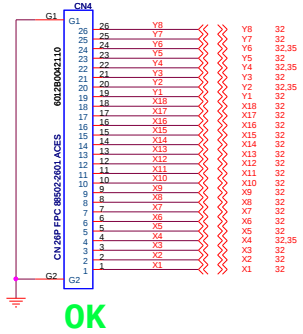
BAP31 (Penryn+Contiga+ICH9M) Motherboard

SIZE: Custom CODE: X01 DOC NUMBER: D-CS-1310A2264501-ALG REV: X01

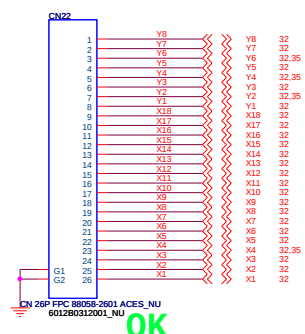
CHANGE by: Millis Lin DATE: Tuesday, March 10, 2009 SHEET: 33 of 36

To K/B(For JM31,BAP31)

To K/B (For SJM31)



OK

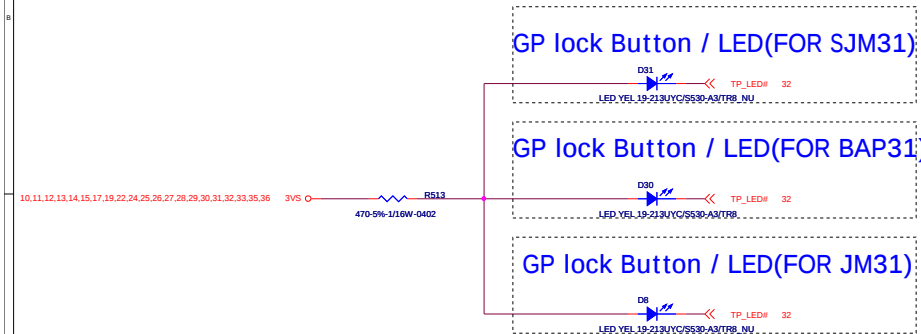


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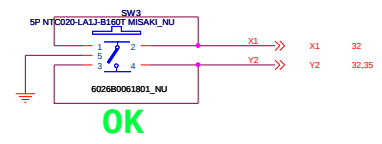
GP lock Button / LED(FOR SJM31)

GP lock Button / LED(FOR BAP31)

GP lock Button / LED(FOR JM31)

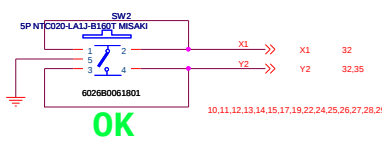


SW (FOR SJM31)



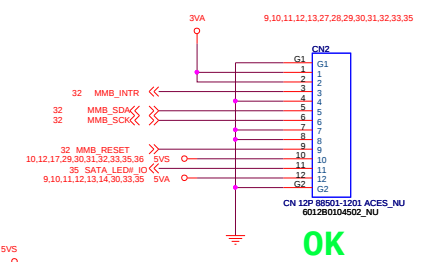
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SW (FOR JM31,BAP31)

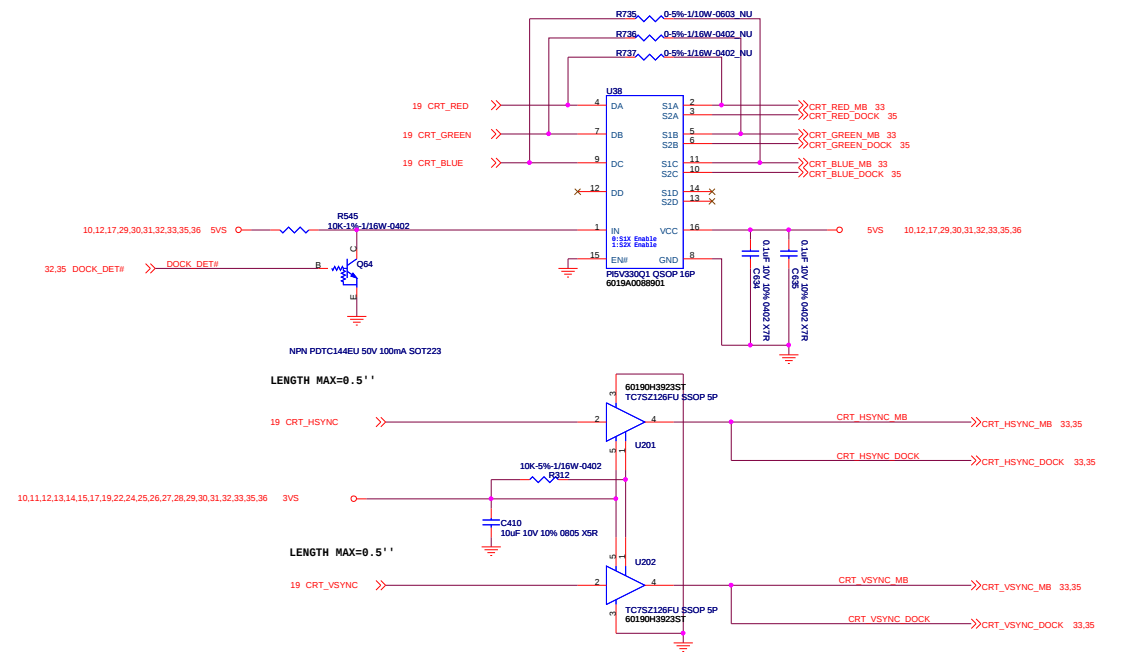


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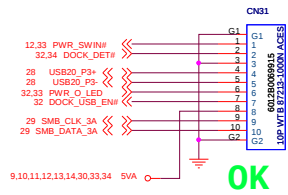
SW Sensor BOARD(For JM31,SJM31)



OK

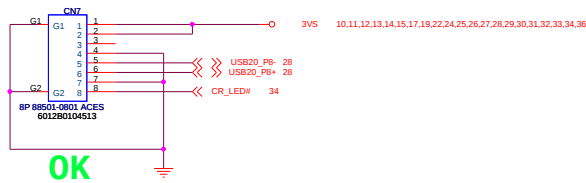


MB(USB) TO EASY/B



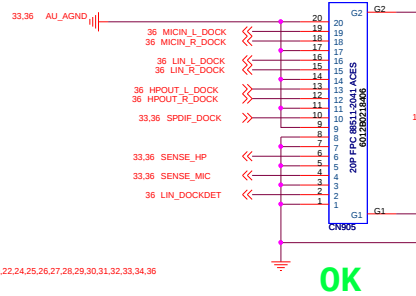
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Card Reader BOARD CN



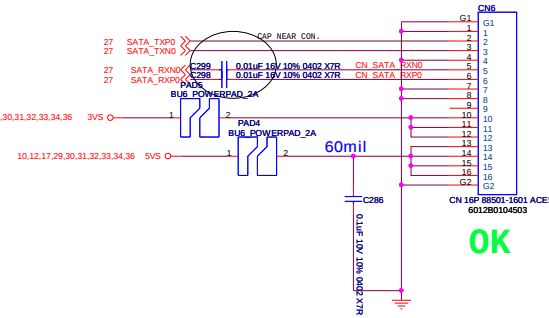
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MB(AUDIO) TO EASY/B(For BAP31)



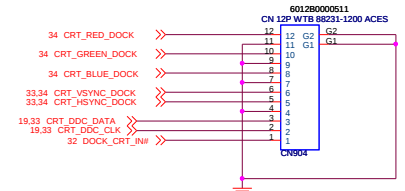
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SSD I/F

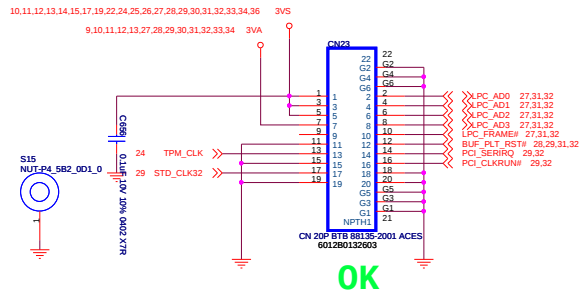


OK

MB(RGB) TO EASY/B

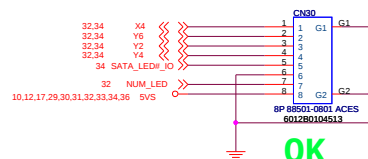


TPM CN



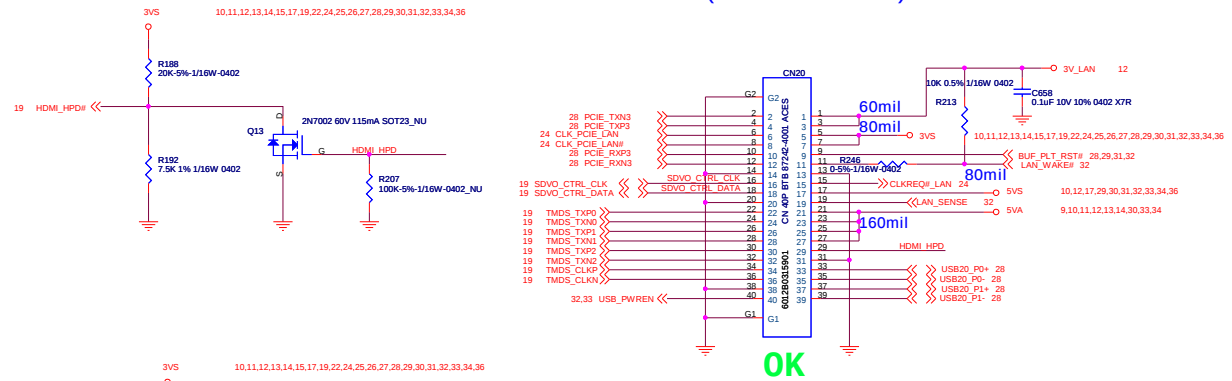
OK

SW/B CN



OK

USB Board CN (LAN+HDMI+2USB)



OK

INVENTEC

TITLE
BAP31 (Penryn+Cantiga+ICH9M)SFF

SIZE CODE DOC NUMBER REV
Custom X01 D-CS-1310A2264501-ALG X01
SHEET 35 of 36

CHANGE by Miles Lin DATE Tuesday, March 10, 2009

